



# Lead-Free Solder Paste

## PF602-P30

Rev. 2019/01/09 Ver. 03-01

### BASIC OVERVIEW



Sn42Bi58 Solder Paste  
 No Clean  
 Zero Halogen  
 Low Melting Point

### APPLICATIONS

The Solder Paste is Intended for Industrial Use Only  
 Low Melting Point Lead-Free SMD Solder Paste  
 Wide Range of Applications and PCB designs

### SPECIFICATION

Appearance	Gray paste w/o visible foreign and clusters		
Alloy Composition	Sn42/Bi58		JIS-Z-3282
Melting Point	139°C		
Particle Size	(Type 3)	20µm - 45µm	J-STD-005
	(Type 4)	20µm - 38µm	
Powder Shape	Spherical		
Flux Content	10 ± 1.0 wt%		JIS-Z-3197
Viscosity	170 ± 50 Pa.s (25±1°C, 10rpm, Malcom)		JIS-Z-3284
Flux Type	ROLO		J-STD-004

### ALLOY COMPOSITION

(Sn)	(Bi)	(Ag)	(Cu)	(Ni)	(Pb)	(Sb)	(Cd)	(Au)	(In)	(Al)	(As)	(Fe)	(Zn)
REM.	57.0~ 59.0	0.10 MAX	0.05 MAX	0.01 MAX	0.05 MAX	0.05 MAX	0.002 MAX	0.05 MAX	0.10 MAX	0.001 MAX	0.03 MAX	0.02 MAX	0.001 MAX

(wt%)



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### PERFORMANCE & RELIABILITY

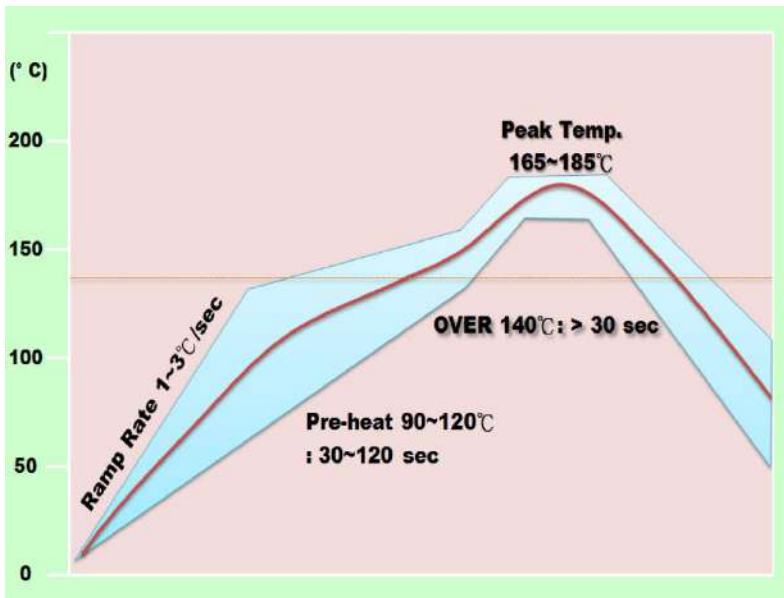
Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Halogen Content Test	ROLO	BS EN14582
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C,10 rpm)	170 ± 50 Pa.s	JIS-Z-3284
Spreading Test	> 70%	JIS-Z-3197
Slump Test	Pass	JIS-Z-3284

S.I.R. Test ▲	Pass	IPC-TM-650, 2.6.3.7
Electro Migration Test ◆	Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions: 40°C, 90% RH for 168hrs

◆ Test Conditions: 65°C, 88.5% RH for 596 hrs

### RECOMMENDED REFLOW PROFILE



Ramp Up Rate (30-90°C): 1.0-3.0°C/s

Pre-heating Time (90-120°C): 30-120s

Time Period Above 140°C: &gt; 30s

Peak Temperature: 165-185°C

Ramp Down Cooling Rate: 1.0-6.0°C/s

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.



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### STORAGE & HANDLING:

- Refrigerate solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away from direct sunlight.
- Allow paste to reach ambient temperature (22-28°C) prior to use for 3-4 hrs. Do not heat up solder paste abruptly.
- Well mix paste with plastic spatula for 1min before use (jars packaging).
- It is recommended to finish fresh paste within 24 hrs. To maintain paste quality, make sure not to store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hr, remove the remained paste from the stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.
- To clean up printed circuit boards, it is suggested to use ethanol or isopropanol.

*Note: For more information, please refer to solder paste application guideline sheet*

### HOW TO ORDER

## PF602 – P30 – T4 – 500

Solder Alloy  
PF602 = Sn42/Bi58

Flux  
P30 = ROL0

Particle Size  
T3 = 20-45µm  
T4 = 20-38µm

Weight / Packaging  
30 = syringe 30g  
100 = syringe 100g  
150 = syringe 150g  
250 = plastic jar 250g  
500 = plastic jar 500g  
600 = small cartridge 600g  
1200 = large cartridge 1200g



### CONTACTS

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